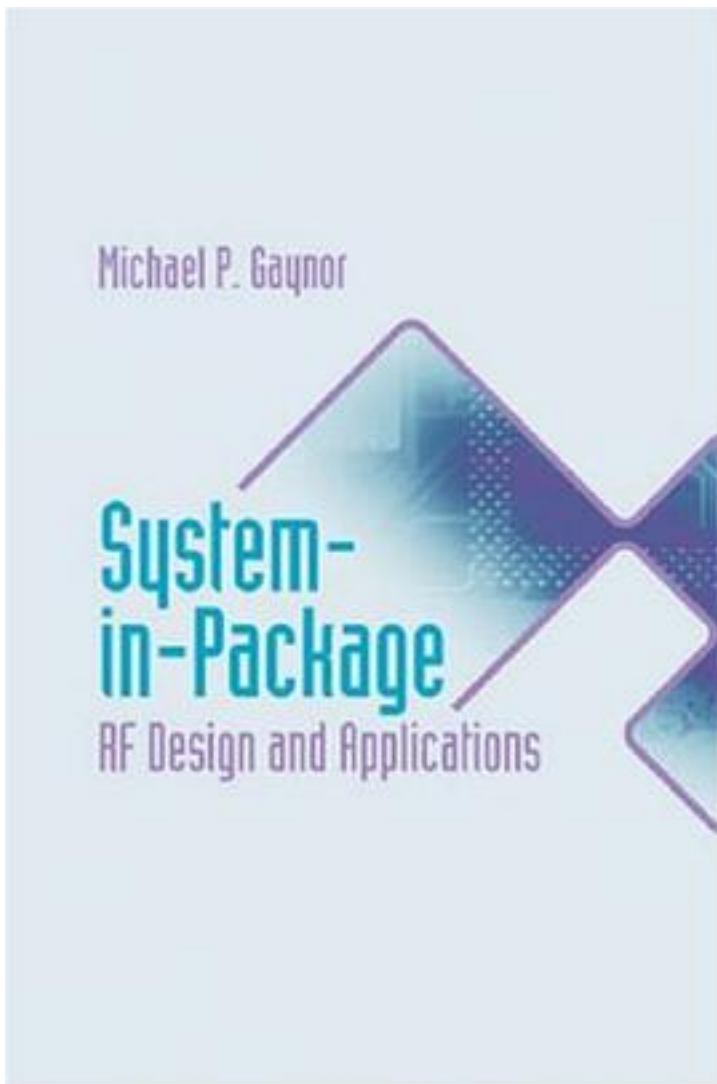


# System-in-Package RF Design and Applications



[System-in-Package RF Design and Applications\\_ 下载链接1](#)

著者:Gaynor, Michael P.

出版者:Artech House

出版时间:2006-12

装帧:HRD

isbn:9781580539050

In the past few years, System in Package (SiP) design has fueled a revolution in the use of modules in wireless devices due its effectiveness in meeting the increasingly demanding requirements for reliability, shielding, performance, size, and cost. Here's the first comprehensive resource on SiP design techniques that offers designers state-of-the-art packaging know-how. Moreover, the book provides numerous examples that illustrate real-world capabilities, constraints, trade-offs, and options at every step.

作者介绍:

目录:

[System-in-Package RF Design and Applications\\_ 下载链接1](#)

标签

SiP

RF

评论

-----  
[System-in-Package RF Design and Applications\\_ 下载链接1](#)

书评

-----  
[System-in-Package RF Design and Applications\\_ 下载链接1](#)